

# Bill of Materials

TI DESIGNS

TIDM-REMOTE-CONTROLLER-FOR-AC

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
1	8	C1,C2,C3,C5,C7,C10,C11,C15	0.1uF	Capacitor,104,0805,6.3V	Murata	GRM21AB10J104M		0805	
2	2	C4,C6	20pF	Capacitor,200,0805,6.3V	Murata	GRM21AB10J200M		0805	
3	2	C8,C14	10uF	Capacitor,106,1206,6.3V	Murata	GRM21AB10J106M		1206	
4	1	C9	1uF	Capacitor,105,0805,6.3V	Murata	GRM21AB10J105M		0805	
5	1	C16	100pF	Capacitor,101,0805,6.3V	Murata	GRM21AB10J101M		0805	
6	1	C12	4.7uF	Capacitor,4.7uF,1206,6.3V	Murata	GRM21AB10J476M		1206	
7	1	C13	100uF	Cap Dip Capacitor,100uF,10V	Murata			0805	
8	1	R1	1M0hm	Resistor,0805,1M,5%	Fenghua	RC05K10003L		0805	
10	1	R3	47K0hm	Resistor,0805,47K,5%	Fenghua	RC05K473L		0805	
11	1	R4	2Kohm	Resistor,0805,2K,5%	Fenghua	RC05K23L		0805	
12	3	R2,R5,R6	00hm	Resistor,0805,0R,5%	Fenghua	RC05K0R0L		0805	
13	1	R7	2.20hm	Resistor,0805,2R2,5%	Fenghua	RC05K2R2L		0805	
14	1	R8	3000hm	Resistor,0805,300R,5%	Fenghua	RC05K300RL		0805	
15	1	R9	220hm	Resistor,0805,220R,5%	Fenghua	RC05K220RL		0805	
16	1	R10	100hm	Resistor,0805,10R,5%	Fenghua	RC05K10RL		0805	
17	1	R11	100K0hm	Resistor,0805,100K,5%	Fenghua	RC05K1003L		0805	
18	1	U1	16K FRAM low powerMCU	MCU	Texas Instruments	MSP430FR4133		TSSOP-56	
19	1	J1	4x32 Segment LCD	LCD					
20	1	LED1	---	INFRARED RADIATION					
21	2	U2	1.5V	AAA battery	Nanfu				
22	1	P1	4-PIN switch	JTAG Port					
23	1	LED2	whilte LED	LED					
24	2	Q1,Q2	NPN Bipolar Transistor	NPN Transistor	On Semi	MMBT3904		SOT-23	
25	1	Crystal	32.768Hz	32.768Khz Crystal,20ppm	Epson	C-004R		DIP-2	

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